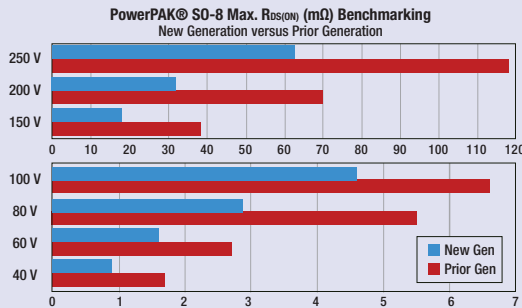




POWER MOSFET | IN A NUTSHELL

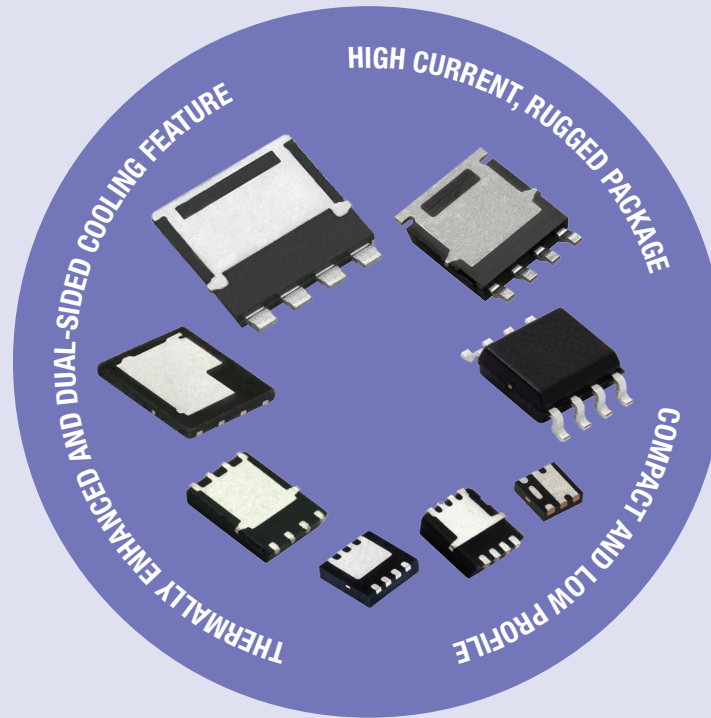
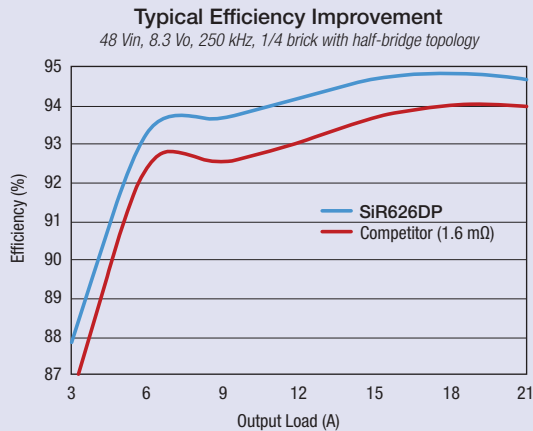
MEDIUM VOLTAGE TrenchFET®

Breakdown voltages: **40 V to 250 V**



Industry's lowest $R_{DS} - Q_{OSS}$
Figure-of-merit (FOM) in an advanced package array

Excellent dynamic parameters optimize switching characteristics



Enable the **HIGHEST** efficiency
↑ INCREASE power density
↓ REDUCE component count
COMPACT and **HIGHLY EFFICIENT** devices enable layout optimization



80 % footprint reduction from D2PAK
75 % lower package profile

APPLICATIONS



Double-cooled PowerPAK SO-8

THIN PROFILE with 0.56 mm typical height
 Footprint **COMPATIBLE** to PowerPAK SO-8
 $R_{DS(ON)}$ as low as **0.73 mΩ**